
2.1.3 HEM assembly

The full assembly data can be found in the document “*HEM_C2_Assembly_Top*” and
“*HEM_C2_Assembly_Bottom*”.

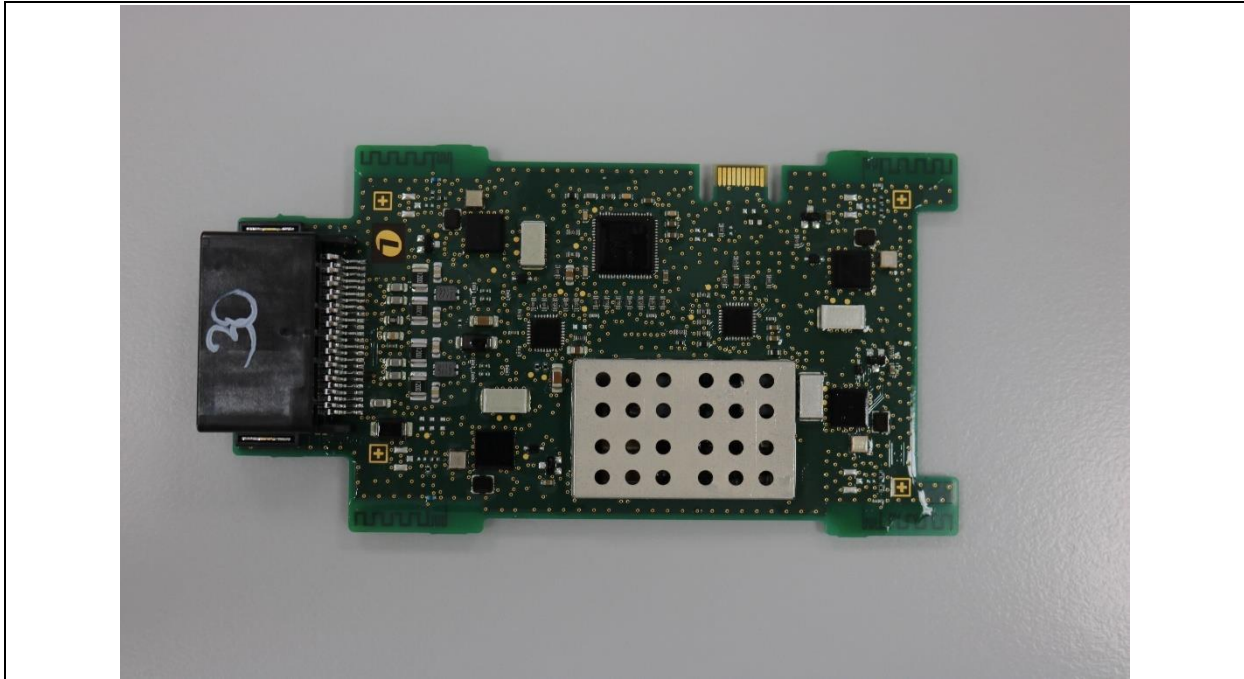


Illustration 1: HEM assembly Top

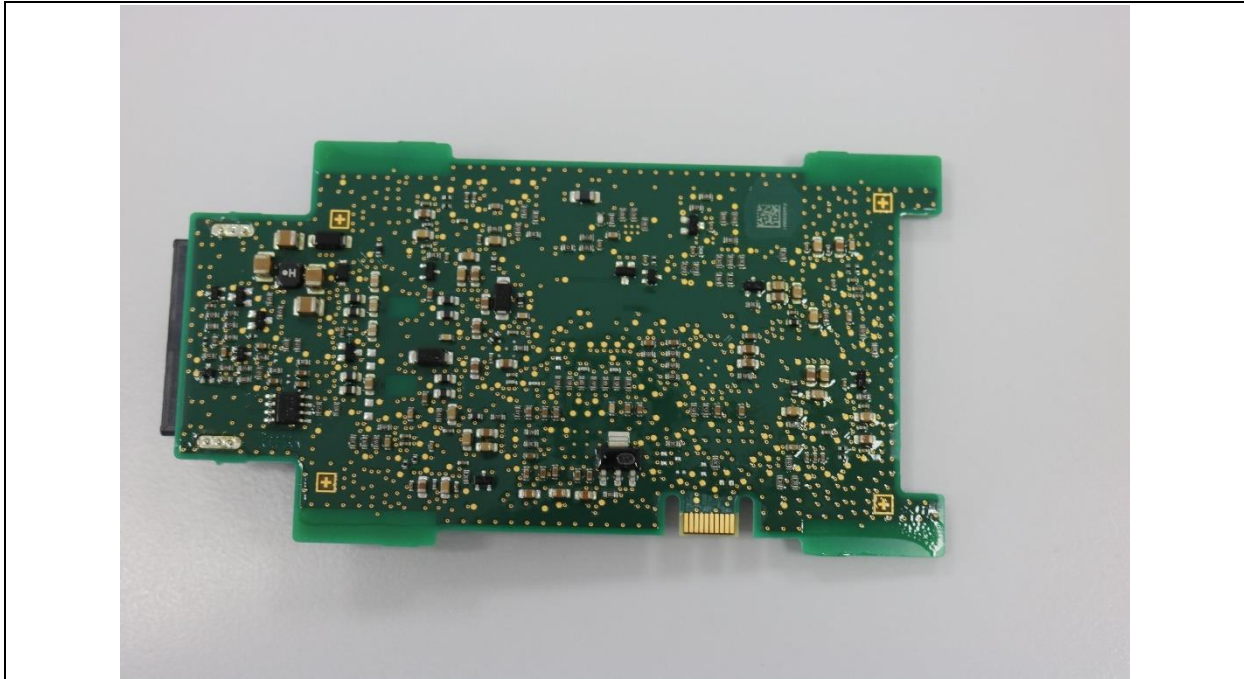


Illustration 2: HEM assembly Bottom

2.1.4 HEM EMC shield

For EMC reasons, the HEM received a EMC shielding around all SMPS components.

This shield consists out of a EMC frame and a EMC cover. The EMC frame is directly soldered to the PCB while the EMC cover is then just clamped on the EMC frame.

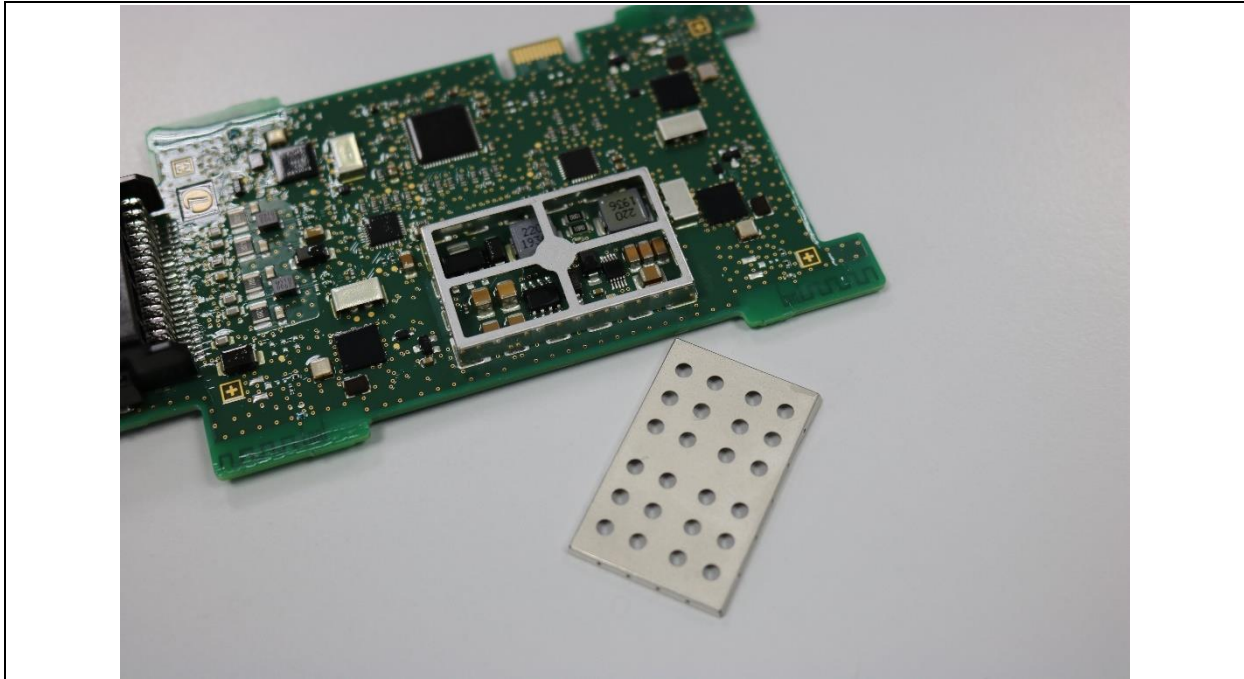


Illustration 3: EMC frame and cover

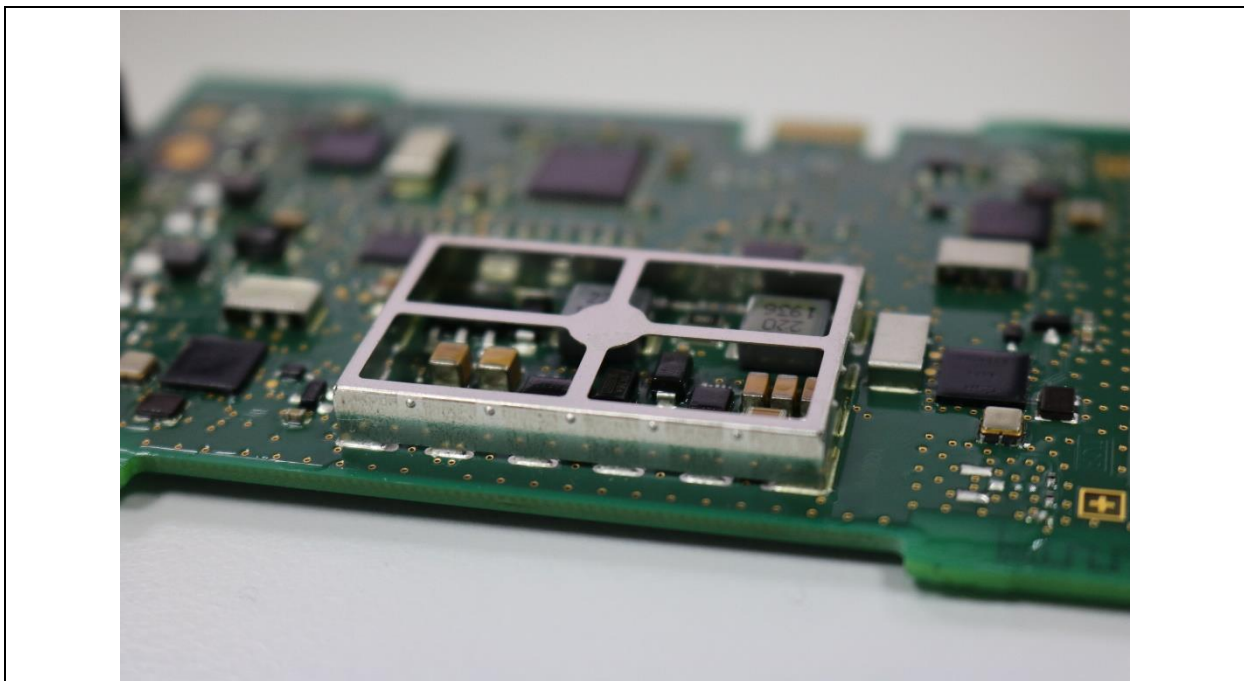


Illustration 4: EMC frame

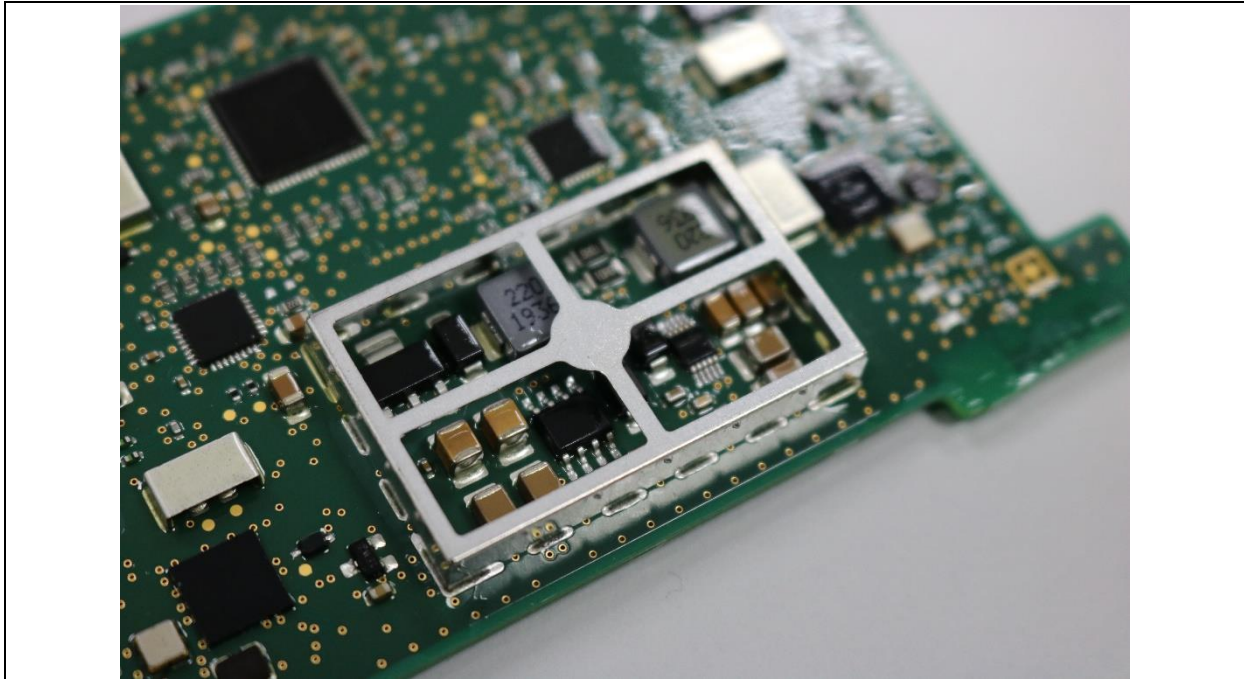


Illustration 5: EMC frame with components inside

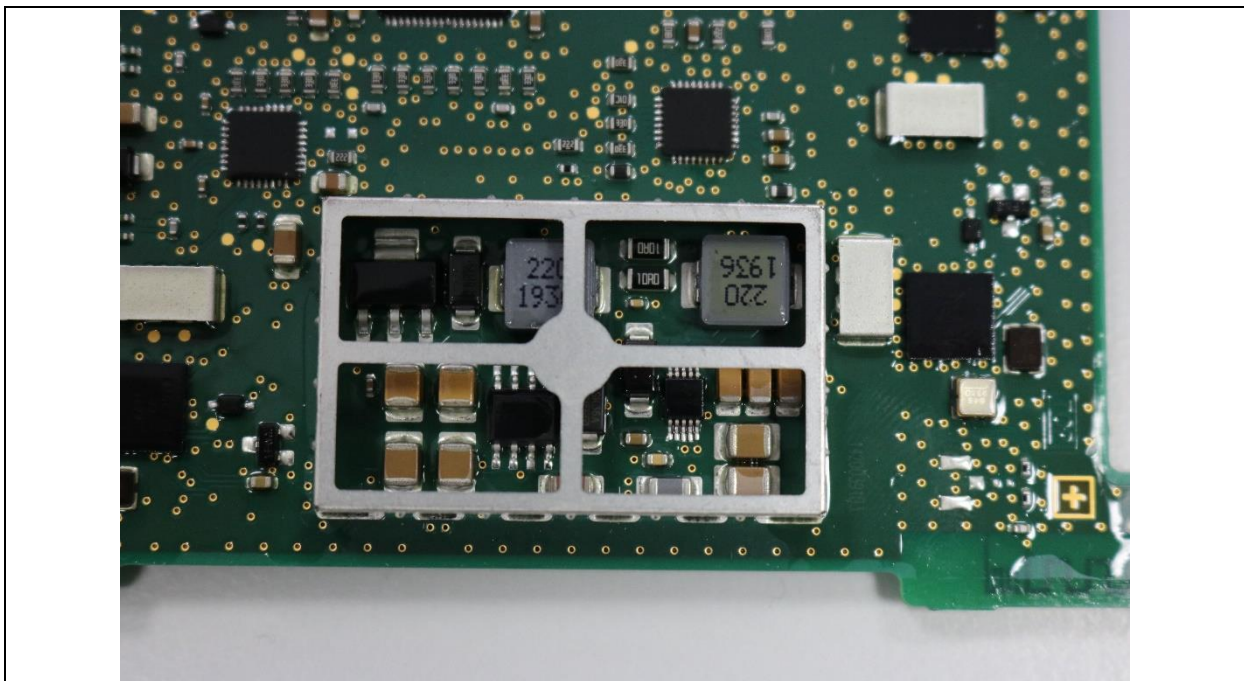


Illustration 6: Components inside the EMC shielding

2.1.7 HEM Antenna

The HEM includes four Bluetooth antennas.

These antennas are microstrip-antennas which are directly on the PCB:

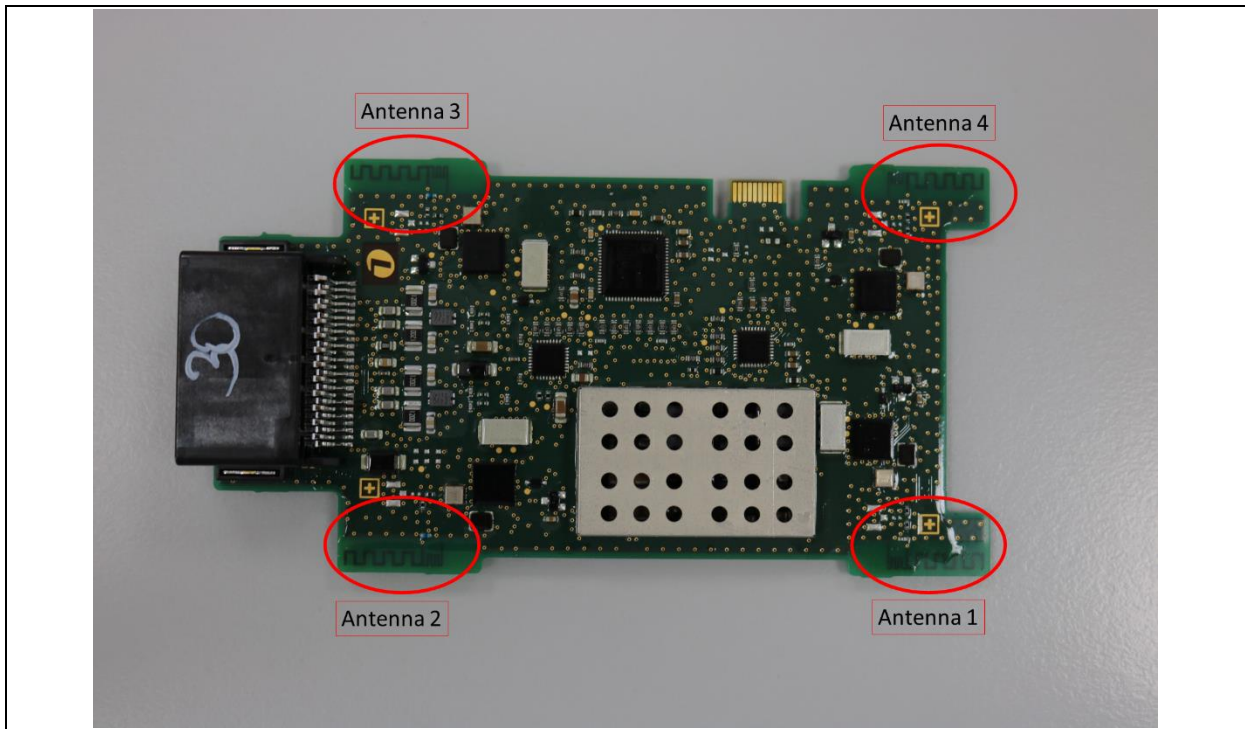


Illustration 7: HEM antennas

The antenna characteristics can be found in the document “HEM_C2_Antenna_Characteristic”.

JLR ADC HEM C2 Sample

**Technical document and general
information**



LEAR Corporation Engineering GmbH
